

WEIDACHENG INDUSYRY CO.,LTD

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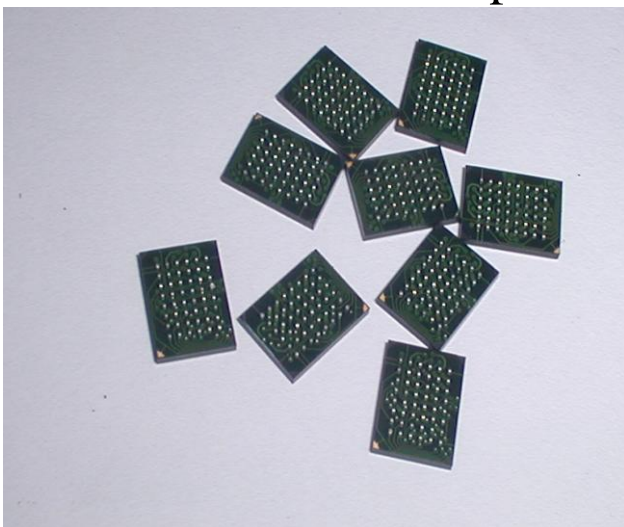
SOLDERING PLACEMENT' SYSTEM BU-550E

Ball placement capability: $\Phi 0.35 \sim \Phi 0.76$

Ball placement range:L-60mm.W-80mm



Solder ball placement for BGA, CSP-IC.



Solder ball collecting bottle base. (Ball cleaning device)



550E-BGA fixtures.

External nitrogen connection.
(For solder ball oxidation prevention)

